

<Intelligent Power Modules>

PM450CGC060

FLAT-BASE TYPE INSULATED PACKAGE



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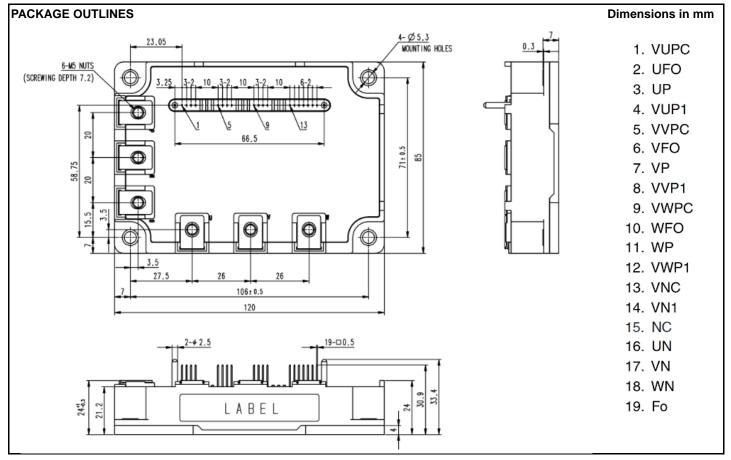
FEATURE

a) Adopting Full-Gate CSTBT[™] chip.

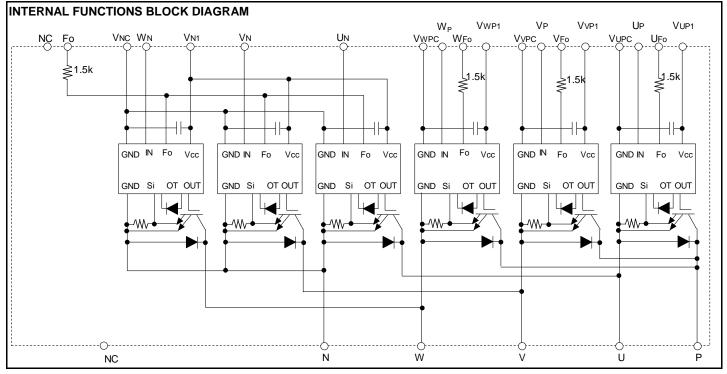
- b) The over-temperature protection which detects the chip surface temperature of CSTBT[™] is adopted.
- c) Error output signal is possible from all each protection upper and lower arm of IPM.

APPLICATION

General purpose inverter, servo drives and other motor controls







MAXIMUM RATINGS ($T_j = 25^{\circ}C$, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions	Ratings	Unit
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	600	V
Ic		T _c =25 °C	450	
I _{CRM}	Collector Current	Pulse	900	A
P _{tot}	Total Power Dissipation	T _c =25 °C	1041	W
le	Emitter Current	T _c =25 °C	450	
I _{ERM}	(Free-wheeling Diode Forward current)	Pulse	900	A
Tj	Junction Temperature		-20 ~ +150	°C

*: Tc measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Conditions	Ratings	Unit
VD	Supply Voltage	Applied between: V _{UP1} -V _{UPC} , V _{VP1} -V _{VPC} , V _{WP1} -V _{WPC} , V _{N1} -V _{NC}	20	V
V _{CIN}	Input Voltage	Applied between: U_P - V_{UPC} , V_P - V_{VPC} , W_P - V_{WPC} , U_N , V_N , W_N - V_{NC}	20	V
V _{FO}	Fault Output Supply Voltage	Applied between: U_{FO} - V_{UPC} , V_{FO} - V_{VPC} , W_{FO} - V_{WPC} , FO- V_{NC}	20	V
I _{FO}	Fault Output Current	Sink current at U_{FO} , V_{FO} , W_{FO} , Fo terminals	20	mA

TOTAL SYSTEM

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC(PROT)}	Supply Voltage Protected by SC	V_D =13.5 V~16.5 V, Inverter Part, T_j =+125°C start	400	V
V _{CC(surge)}	Supply Voltage (Surge)	Applied between: P-N, Surge value	500	V
T _{stg}	Storage Temperature	-	-40 ~ +125	°C
V _{isol}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V

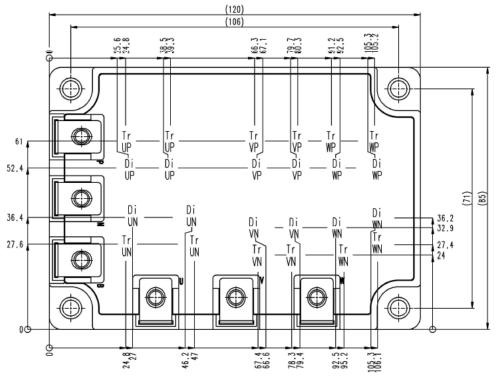
*: Tc measurement point is just under the chip.



THERMAL RESISTANCE

Symbol	Parameter	Conditions	Limits			Unit
	Falameter	Conditions	Min.	Тур.	Max.	Unit
R _{th(j-c)Q}	Thermal Resistance	Junction to case, IGBT, per 1 element (Note1)	-	-	0.12	
R _{th(j-c)D}		Junction to case, FWD, per 1 element (Note1)	-	-	0.16	к/w
R _{th(c-s)}	Contact Thermal Resistance	Case to heat sink, per 1 module,		0.015	_	
		Thermal grease applied (Note.1)	-	0.015	-	

Note1. If you use this value, $R_{\text{th}(s \text{-}a)}$ should be measured just under the chips.



ELECTRICAL CHARACTERISTICS (T_j= 25°C, unless otherwise noted)

INVERTER PART

Symbol	Parameter	Conditions		Limits			Unit
Symbol	Parameter			Min.	Тур.	Max.	Unit
V	Collector-Emitter Saturation Voltage	V _D =15 V, I _C =450 A	T _j =25 °C	-	2.00	2.60	v
V _{CEsat}		V _{CIN} =0 V, Pulsed, Terminal (Fig.1)	T _j =125 °C	-	2.00	2.60	v
V _{EC}	Emitter-Collector Voltage	I_E =450 A, V_D =15 V, V_{CIN} = 15 V, Terminal	(Fig.2)	-	1.60	2.70	V
t _{on}		$V_D=15 \text{ V}, V_{CIN}=0 V \leftrightarrow 15 V,$		-	0.9	-	
t _{rr}		V _{cc} =300 V, I _c =450 A, T _j =125 °C, Inductive Load		-	0.2	-	
t _{c(on)}	Switching Time			-	0.3	-	μs
t _{off}				-	1.2	-	
t _{c(off)}		(Fig.3, 4)		-	0.3	-	
	Collector Emitter Cut off Current		T _j =25 °C	-	-	1	~ ^
ICES	Collector-Emitter Cut-off Current	llector-Emitter Cut-off Current $V_{CE}=V_{CES}, V_D=15 V, V_{CIN}=15 V$ (Fig.5)	T _j =125 °C	-	-	10	mA



ELECTRICAL CHARACTERISTICS (cont.; T_j = 25°C, unless otherwise noted)

CONTROL PART

Symbol	Parameter	Conditions	Conditions		Limits		
Symbol	Parameter	Conditions			Тур.	Max.	Unit
1			V _{P1} -V _{PC}	-	2	4	
ID	Circuit Current	V _D =15 V, V _{CIN} =15 V	V _{N1} -V _{NC}	-	6	12	mA
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8	v
$V_{th(OFF)}$	Input OFF Threshold Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, V_{N}$	U_P-V_{UPC} , V_P-V_{VPC} , W_P-V_{WPC} , U_N , V_N , W_N-V_{NC}		2.0	2.3	
SC	Short Circuit Trip Level	-20≤T _j ≤125 °C, V _D =15 V (Fig.3, 6)		675	-	-	Α
$t_{off(SC)}$	Short Circuit Current Delay Time	V _D =15 V (Fig.3, 6)	V _D =15 V (Fig.3, 6)		0.2	-	μs
ОТ	Over Temperature Distoction	Detect Temperature of ICBT ship	Trip level	150	-	-	°C
OT _(hys)	Over Temperature Protection	Detect Temperature of IGBT chip	Hysteresis	-	20	-	
UVt	Supply Circuit	2047 4125 %	Trip level	11.5	12.0	12.5	v
UVr	Under-Voltage Protection	-20≤Tj≤125 °C	Reset level	-	12.5	-	
I _{FO(H)}	Foult Output Outpot	\/1E_\/_\/1E_\/_(Nete2)	·	-	-	0.01	
I _{FO(L)}	Fault Output Current	V _D =15 V, V _{FO} =15 V (Note2)		-	10	15	mA
t _{FO}	Fault Output Pulse Width	V _D =15 V (Note2)		1.0	1.8	-	ms

Note2. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

MECHANICAL RATINGS AND CHARACTERISTICS

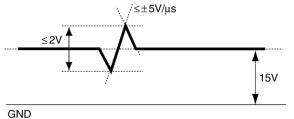
Symbol	Parameter	Conditions		Limits		
	Faldneter			Тур.	Max.	Unit
Ms	Mounting Torque	Mounting part screw : M5	2.5	3.0	3.5	N•m
Mt	Mounting Torque	Main terminal part screw : M5	2.5	3.0	3.5	N•m
m	mass	-	-	575	-	g

RECOMMENDED CONDITIONS FOR USE

Symbol	Parameter	Conditions	Recommended value	Unit
V _{cc}	Supply Voltage	Applied across P-N terminals	≤ 400	V
V _D	Control Supply Voltage	Applied between : V _{UP1} -V _{UPC} , V _{VP1} -V _{VPC} , V _{WP1} -V _{WPC} ,V _{N1} -V _{NC} (Note3)	15.0±1.5	V
V _{CIN(ON)}	Input ON Voltage	Applied between :	≤ 0.8	V
V _{CIN(OFF)}	Input OFF Voltage	$U_{P}\text{-}V_{UPC}, V_{P}\text{-}V_{VPC}, W_{P}\text{-}V_{WPC}, U_{N}, V_{N}, W_{N}\text{-}V_{NC}$	≥ 9.0	v
f _{PWM}	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.0	μs

This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

Note3. With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5$ V/µs, Variation ≤ 2 V peak to peak





PRECAUTIONS FOR TESTING

- 1. Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
- After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V_{CES} rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)

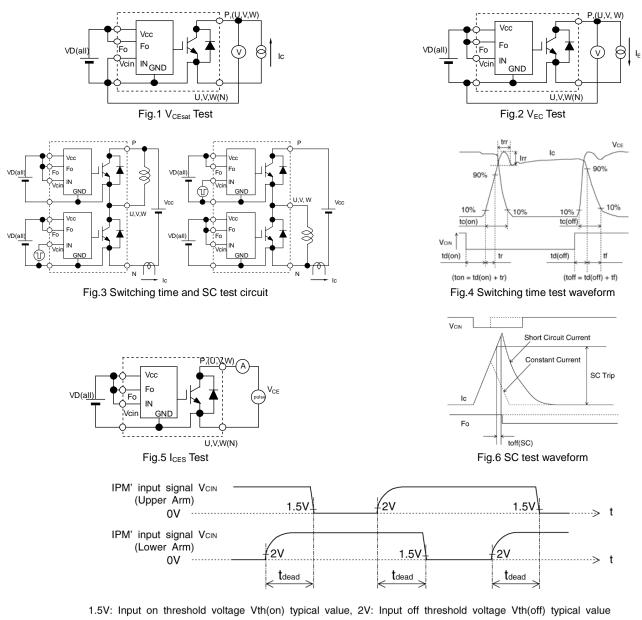
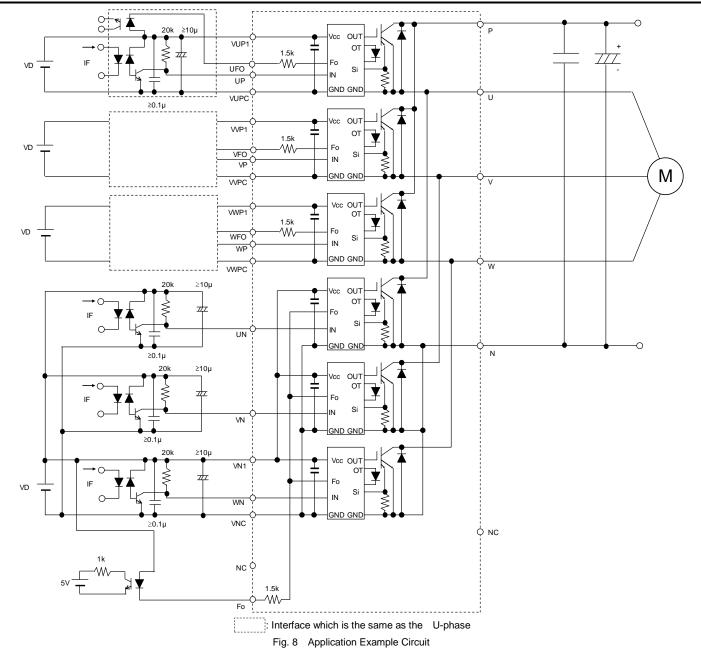


Fig. 7 Dead time measurement point example



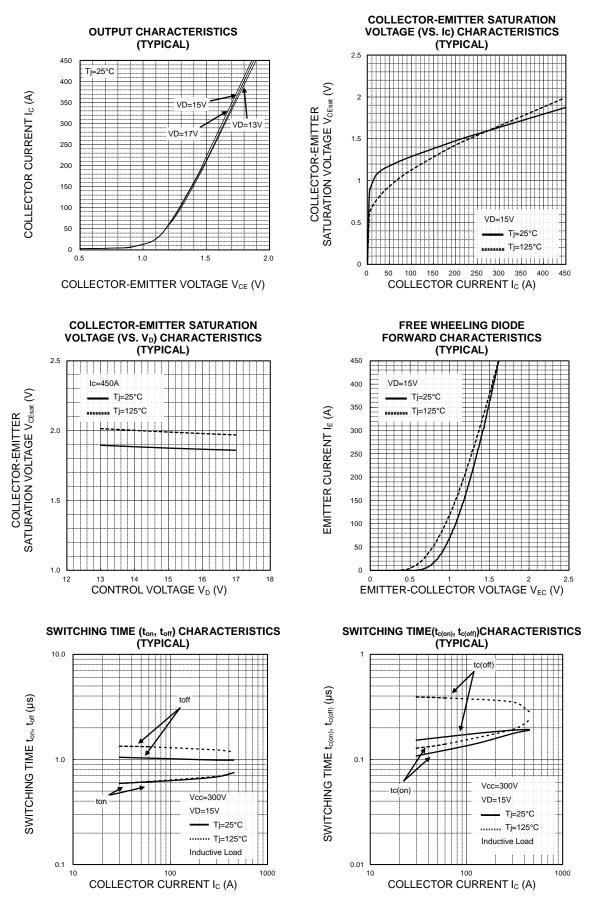


NOTES FOR STABLE AND SAFE OPERATION ;

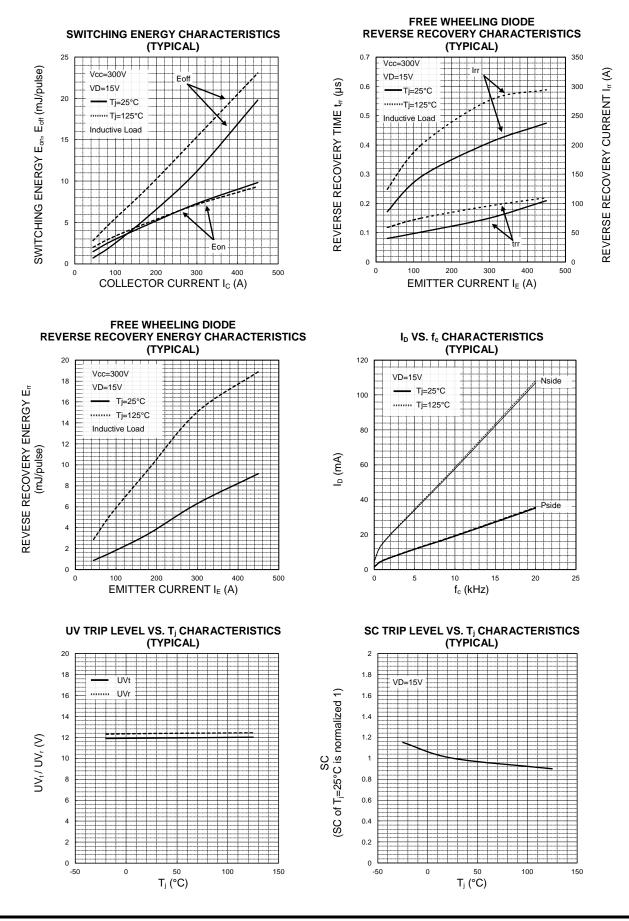
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t_{PLH} , $t_{PHL} \le 0.8 \mu s$, Use High CMR type.
- Slow switching opto-coupler: CTR > 100%
- Use 4 isolated control power supplies (V_D). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.



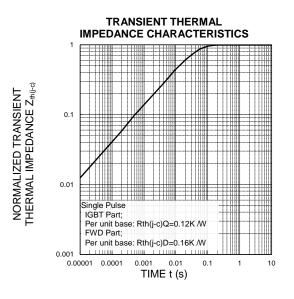
PERFORMANCE CURVES













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